DECLARATION OF CONFORMITY
Annex II to Directive 2011/65/EU and its amendment Directive (EU) 2015/863 (RoHS)

Manufacturer's Name: VENTILATION SYSTEMS, LLC

Manufacturer's Address: Kotsiubynskoho Mykhaila Street (Shevchenkivskyi District),
building 1, Kyiv, UA-01054, Ukraine

Declares that the product

Product Name: Axial decorative fans for extract ventilation with low power consumption

Model Number: Plastic Heat Exchanger
Trade Mark: ZERN

Conforms to the following Product Specifications:

We hereby declare that total concentration of Lead, Cadmium, Mercury, Chromium VI, Polybrominated Biphenyls (PBBs), Polybrominated Diphenyl Ethers (PBDEs), Bis (2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) and Diisobutyl phthalate (DIBP) in Electrical and Electronic Equipment in accordance with EC Directive 2011/65/EU and its amendment Directive (EU) 2015/863 (RoHS):

Parameter	**Permitted Level**	
1	2	
Lead (Pb)	<0.1%	1000ppm
Cadmium (Cd)	<0.01%	100ppm
Hexavalent Chromium (Cr VI)	<0.1%	1000ppm
Mercury (Hg)	<0.1%	1000ppm
Polybrominated biphenyls (PBBs)	<0.1%	1000ppm
Polybrominated diphenyl ether (PBDEs)*	<0.1%	1000ppm
Bis(2-ethylhexyl) phthalate (DEHP)**	<0.1%	1000ppm
Butyl benzyl phthalate (BBP)**	<0.1%	1000ppm
Dibutyl phthalate (DBP)**	<0.1%	1000ppm
Diisobutyl phthalate (DIBP)**	<0.1%	1000ppm

* This includes also DecaBromoDiphenylEther (Deca-BDE).
** In accordance with amendment under Commission Delegated Directive (EU) 2015/863 of 31 March 2015.

VENTILATION SYSTEMS RoHS compliant devices contain no more than 0.1% lead (Pb) by weight per homogeneous material, unless used in an application exempted by RoHS. VENTILATION SYSTEMS may declare the use of the following RoHS exemptions for RoHS compliant semiconductor devices:

RoHS Exemption	RoHS Exemption Description***
6(c)	Copper alloy containing up to 4 % lead by weight
7(a)	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

7(c)-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound
15	Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages
15(a)	Lead in solders to complete a viable electrical connection between the semiconductor die and carrier within integrated circuit flip chip packages where at least one of the following criteria applies: - a semiconductor technology node of 90 nm or larger; - a single die of 300 mm^2 or larger in any semiconductor technology node; - stacked die packages with die of 300 mm^2 or larger, or silicon interposers of 300 mm^2 or larger.

*** Applicable within the scope of categories and expiry dates as given in Annex III of Directive 2011/65/EU

Any device that VENTILATION SYSTEMS has certified as RoHS compliant declaring Exemption 15 or 15(a) will contain lead (Pb) in solders. These products are RoHS compliant when used in OEM applications covered by these RoHS exemptions permitting lead in solders for applicable categories; expiration dates as listed in Annex III of Directive 2011/65/EU. Applicability of Exemption 15 or 15(a) is dependent on OEM application and final use.

Certification of RoHS compliance of VENTILATION SYSTEMS products is reliant upon VENTILATION SYSTEMS supplier material content data certifications of each supplied homogenous material in a product(s). The signature below verifies that statements above, including but not limited to material composition data are valid and accurate to the best of our knowledge for VENTILATION SYSTEMS products in original sale condition.

Responsible for marking this declaration is the:
Manufacturer [X] **Authorized representative established within the EU [ ]**

Person responsible for making this declaration:
Name, surname: Valeriy Kolomiychenko

Position/ Title: Managing director
Kyiv **2025/07/14**
(Place) (Date)

«ВЕНТИЛЯЦІЙНІ СИСТЕМИ»
Ідентифікаційний код 30637114